Z21 Max Chip Tin Station

Description:

Z21 MAX chip tin station CPU reballing stencil platform for iPhone 6-14 Pro Max A8-A16 CPU, Android phone. MJ Z21 MAX CPU IC lead embedding platform with iron mesh for Android iPhone CPU repair. MIJING Z21 MAX CPU reballing stencil platform for iPhone A8 A9 A10 A11 A12 A13 A14 A15 A16 CPU, Android Huawei Qualcomm, etc.

Features:

- High temperature resistance and abrasion resistance.
- Imported alloy steel, metal fatigue resistance, making the product more durable.
- Dirt-resistant, easy to clean.
- High precision, precise alignment of each mesh is calibrated according to the original factory drawing to ensure the accuracy of the solder joints.
- Square holes and rounded corners are planted with tin and black netting to make each of your tin balls rounder and fuller.
- Rigid and flexible, retaining the flexibility of steel, normal deformation and bending can be easily restored to its original shape.
- High precision, no burrs, so that each mesh can be the same size and not stuck.
- Double magnet, super magnetic, accurate positioning without shaking.

Applicable Models:

- iPhone 6-14 Pro Max CPU (A8 A9 A10 A11 A12 A13 A14 A15 A16 CPU).
- For Huawei HI3670 Huawei HI3680, HiSilicon HI3690, HiSilicon HI3690 5G, HiSilicon HI6290/L Qualcomm SM8250-102 small, Qualcomm SM8250-202 large, Qualcomm SM8350/Snapdragon 888 Snapdragon 845/SDM845, Snapdragon 855/SM8150, Kirin 9000 HI36A0, EMMC 9000 HI36A0 EMCP/UFS BGA153.

Made in China